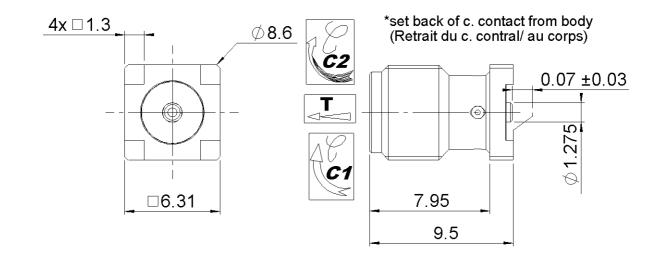
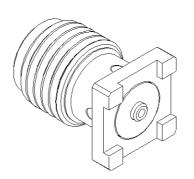
**SMT TYPE - REEL OF 100** 

R124.427.800

Series: SMA-COM







All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (µm)	
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	BRASS BERYLLIUM COPPER - PTFE -	GOLD OVER NICKEL GOLD OVER NICKEL -	
- -	- -	-	

**Issue:** 1138 C

In the effort to improve our products, we reserve the right to make changes judged to be



**SMT TYPE - REEL OF 100** 

R124.427.800

Series: SMA-COM

#### **PACKAGING**

Standard	Unit	Other
100	'W' option	Contact us

## **SPECIFICATION**

# **ELECTRICAL CHARACTERISTICS**

Impedance 50  $\Omega$ Frequency **0-18** GHz

**VSWR**  $1.04 + 0.0450 \times F(GHz) Maxi$ 

Insertion loss **0.05**  $\sqrt{F(GHz)}$  dB Maxi

RF leakage **100** - F(GHz)) dB Maxi

Voltage rating 500 Veff Maxi Dielectric withstanding voltage 1000 Veff mini Insulation resistance **5000** M $\Omega$  mini

## **ENVIRONMENTAL**

**-65/+165** ° C Operating temperature

Hermetic seal NA Atm.cm3/s

Panel leakage NA

## **OTHER CHARACTERISTICS**

Assembly instruction

Others:

FORCE F1:100N-TORQUES C1:70Ncm-C2:90Ncm

# **MECHANICAL CHARACTERISTICS**

Center contact retention

Axial force – Mating end 15 N mini Axial force – Opposite end 15 N mini Torque 1 N.cm mini

Recommended torque

Mating **40** N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

**1.2540** g Weight

**Issue:** 1138 C

In the effort to improve our products, we reserve the right to make changes judged to be



**SMT TYPE - REEL OF 100** 

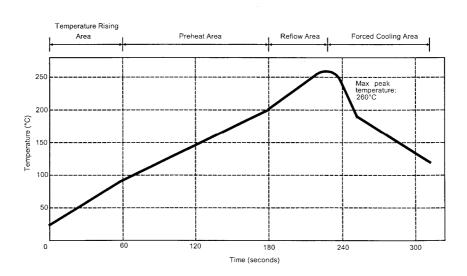
R124.427.800

Series: SMA-COM

# SOLDER PROCEDURE

- 1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
  - We advise a thickness of 150 microns mini (.006 inch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Aspiration port centered into body and push against it.
  - Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

#### TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

**Issue:** 1138 C

In the effort to improve our products, we reserve the right to make changes judged to be

necessary.

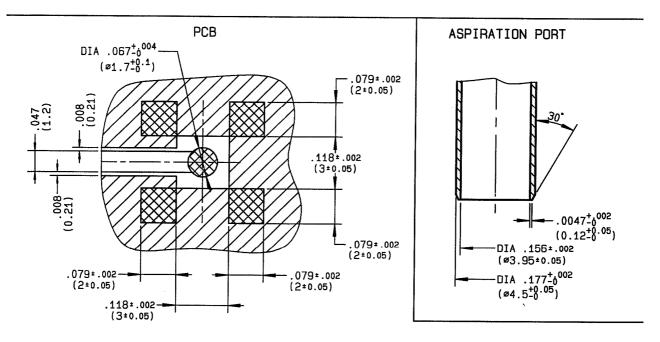


**SMT TYPE - REEL OF 100** 

# R124.427.800

Series: SMA-COM

#### SMA B SERIES - INFORMATIONS



#### COPLANAR LINE

Pattern and signal are on the same side Thickness of PCB: .063 (1.6 mm)
The material of PCB is the epoxy resin of glass fabrics bacs.(Er = 4.8)
The solder resist should be printed exept for the land pattern on the PCB.

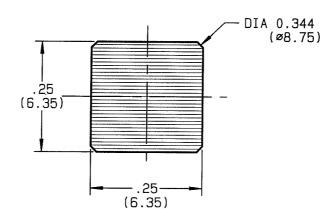


Pattern



Land for solder paste

### SHADOW OF "SMA B" RECEPTACLE FOR VIDEO CAMERA



**Issue :** 1138 C In the effort to improve our products, we reserve the right to make changes judged to be

